BONDING APPARATUS

ABSTRACT OF THE DISCLOSURE

A bonding apparatus has a relay stage for a chip, a bonding head, and a substrate stage. The bonding head and the substrate stage are moved relatively so that the chip is bonded to the substrate. A delivery mechanism having a retention portion for retaining the chip and the substrate is provided movably relatively to the relay stage and the substrate stage. The chip retained by the retention portion is mounted onto the relay stage, while the substrate retained by the retention portion is mounted onto the substrate stage, or while the retention portion retains the substrate mounted on the substrate stage.

Figure 1